



QC dept.
LSI manufacturing HQs
ROHM CO., LTD.

Product Change Notification

Introduction of additional surface finish composition for Pb-free termination

Change Notification #: 200710L-01
Date of issue: 31 October 2007

Applicable Parts: All IC parts manufactured by ROHM

Description of Change: Introduce additional surface finish composition for Pb-free termination and supply two types of composition in parallel.

Reason for Change: Improve production efficiency and secure stable delivery for customers.

Details of Change:

	Current composition	New composition
Composition	Sn-Cu(2%)	Sn(100%) or Sn-Cu(2%)
Plating technology	No change (Electrical plating)	
Part number	No change	
Electrical characteristics	No change	
Recommended soldering profile	No change	
Reliability	No change (Test results available upon request)	

Details of Sn(100%) surface finish

- Plating thickness : Min. 7 μ m
- Underplate : None
- Gloss: Matt
- Post bake: 150°C for 60 min. after plating
- Plating control: Conform to NEMI standard (carbon concentration, grain size and so on)

Date of implementation: 1 December 2007

*Should you have any issues with content of this change, please contact the Rohm sales or marketing person(s).
No response from customers will be deemed as acceptance of the change.*